



## TOM GREEN

Principal,  
TJ Green Associates, LLC

A **veteran-owned small business**, TJ Green Associates, LLC is the recognized industry leader in consulting services, expert witness testimony, and training solutions related to the assembly and packaging of microelectronic components for high-reliability military, space and medical device applications.

**Tom Green, Principal**, has more than 34 years of combined experience in industry/academia and the Department of Defense, including years developing curriculum and teaching industry professionals about microelectronics assembly-related packaging and processes.

For the last 15 years, Tom's expertise has helped position his company as a **recognized industry leader** in teaching and consulting services for high-reliability military, space, and medical device applications.



### EXPERT WITNESS

Having spent time in industry, government research labs, and academia, Tom has gained considerable expertise regarding the materials and processes used in microelectronic packaging. As such, he has become a sought-after expert witness in legal cases involving high-reliability military, space and medical device applications.

He has developed a strong perspective on the many possible root causes of device failures specifically regarding hermetic package sealing and hermeticity related in vivo failures of cochlear implants, neurostimulators and other Class III medical implants.

### CMSE ORGANIZER

The [Annual Components for Military & Space Electronics Conference & Exhibition](#) has become THE premier event focused on the design, reliability, and application of electronic components for use in avionics aerospace, military & commercial space systems. This year's event features more than 30 technical presentations and six cutting-edge, 1/2 day tutorials by industry leaders focused on advanced packaging of ICs, passive components, and a variety of other topics critical to components used in high rel mil and aerospace systems.

### SEMINAR PRESENTER

Stay ahead of your competition and keep your engineering and technical staff current by sharpening your skills with leading-edge seminars that cover a variety of subjects critical to the field of microelectronics packaging. These multi-day seminars, presented by Tom and other industry experts, are typically held at a hotel conference center or professional training facility and are available to anyone in the industry. The most popular seminars are scheduled multiple times around the country and overseas, so there is sure to be a training session that will meet your organization's needs.

### SCRUTINIZING MIL-STD-883 VISUAL INSPECTION CRITERIA

An important consideration in wire bonding is visual inspection of the deformed wire after wire bond formation. The MIL-STD-883 criteria was developed over many years and is intended to cover a broad range of technologies — both TM 2017 and TM 2010 contain much wisdom and still serve as the defacto standard. In some cases, however, the inspection criteria is lenient while in others instances it is overly restrictive. Take a closer look at the baseline requirements in Tom's [blog post](#) and [IMAPS 2017 presentation](#).

Tied to a particular page in MIL-STD-883, Tom's [Workmanship Standards eBook](#) — an online illustrated guide of common workmanship defects as seen during production — is an indispensable resource for those in the industry.

